

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claims 1-10 (canceled).

Claim 11 (new): A shielding apparatus for EMI-sensitive components, comprising:

a first circuit board, having a plurality of layers having interfacial connections, said first circuit board including a first base surface and a recess opening on one layer in which non-EMI-sensitive components are arranged;

a first contact area encompassing the recess opening;

a first earth face, which corresponds to an area of the base surface and the recess opening, wherein the non-EMI-sensitive components are arranged outside the first contact area or the first earth face;

a second circuit board, having a plurality of layers having interfacial connections, said second board including a second base surface on one layer in which EMI-sensitive components are arranged;

a second contact area encompassing the EMI-sensitive components; and

a second earth face, corresponding to an area of the second base surface,

wherein the first and second circuit board are coupled via joining means, and wherein said EMI-sensitive components are arranged within the recess opening of the first printed circuit board, and wherein at least some of the interfacial connections, together with the recess and the first and second earth faces, form a cage in which the EMI-sensitive components are shielded.

Claim 12 (new): The shielding apparatus of claim 11, wherein the first earth face is disposed between the recess opening of the first base surface and a side of the circuit board facing away from the recess opening.

Claim 13 (new): The shielding apparatus of claim 11, wherein the first earth face is disposed in a plane of the first base surface.

Claim 14 (new): The shielding apparatus of claim 11, wherein the first earth face is disposed in a plane of a side of the circuit board facing away from the recess opening.

Claim 15 (new): The shielding apparatus of claim 11, wherein the second earth face is disposed between the EMI-sensitive component circuit board layer and a side facing away from the EMI-sensitive component circuit board layer.

Claim 16 (new): The shielding apparatus of claim 11, wherein the second earth face is disposed in a plane of a side facing away from the EMI-sensitive component circuit board layer.

Claim 17 (new): The shielding apparatus of claim 11, wherein the interfacial connections are spaced apart by a distance less than one-tenth of the wavelength (λ) of an electromagnetic radiation emitted by the components

Claim 18 (new): The shielding apparatus of claim 11, wherein the interfacial connections pass through their respective earth faces.

Claim 19 (new): The shielding apparatus of claim 11, wherein the interfacial connections are filled with a filling material.

Claim 20 (new): The shielding apparatus of claim 19, wherein the filling material is resin-based.

Claim 21 (new): The shielding apparatus of claim 11, wherein the interfacial connections are connected to each respective earth face and to a respective contact area.

Claim 22 (new): The shielding apparatus of claim 21, further comprising two gaps between the second contact area and a respective interfacial

connection having first signal lines, wherein said signal lines transmit signals to and from the EMI-sensitive components on the second circuit board.

Claim 23 (new): The shielding apparatus of claim 22, further comprising two gaps between the first contact area and a respective interfacial connection having second signal lines, wherein said second signal lines are coupled to the first signal lines outside the recess opening.

Claim 24 (new): The shielding apparatus of claim 11, wherein the earth faces are configured as continuous faces.

Claim 25 (new): The shielding apparatus of claim 11, wherein the earth faces are configured as grid faces, with grid line spacing of less than one-tenth of the wavelength (λ) of an electromagnetic radiation emitted by the components.

Claim 26 (new): The shielding apparatus of claim 11, wherein the non-EMI-sensitive components are surface mounted devices.

Claim 27 (new): The shielding apparatus of claim 11, wherein the first contact area includes a first shielding face through which first interfacial connections pass, and a second shielding face through which second interfacial connections pass.